

Abstract:

A method and system for collecting and analyzing photoemission data wherein illumination and photoemission images are acquired for a plurality of die, such as for each die on a wafer. Then, the images are overlaid, aligned, and assembled in a mosaic, thereby allowing analysis of the photoemission occurring across a plurality of die, such as across the entire wafer. Preferably, gathering this data allows statistical analysis of the photoemission such as analysis of commonly emitting locations to identify structures/cells that are sensitive to the manufacturing process.